Electronic Supplementary Material (ESI) for Polymer Chemistry.

Supporting Information

Highly Thermal Conductive Resins formed from Wide-Temperature-Range Eutectic Mixtures of Liquid Crystalline Epoxies Bearing Diglycidyl Moieties at the Side Positions

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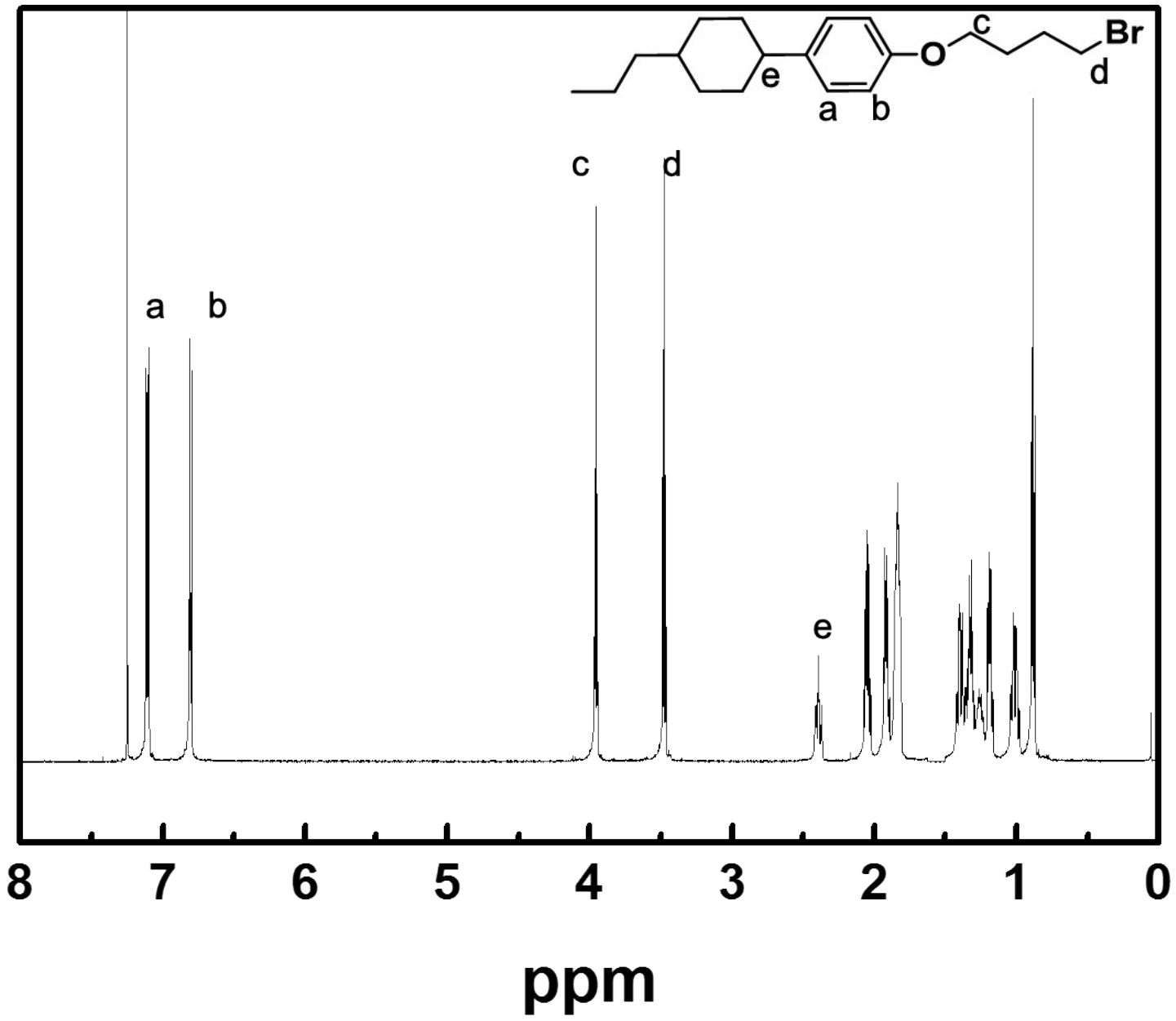

Figure S1. HNMR spectra of PCH304Br

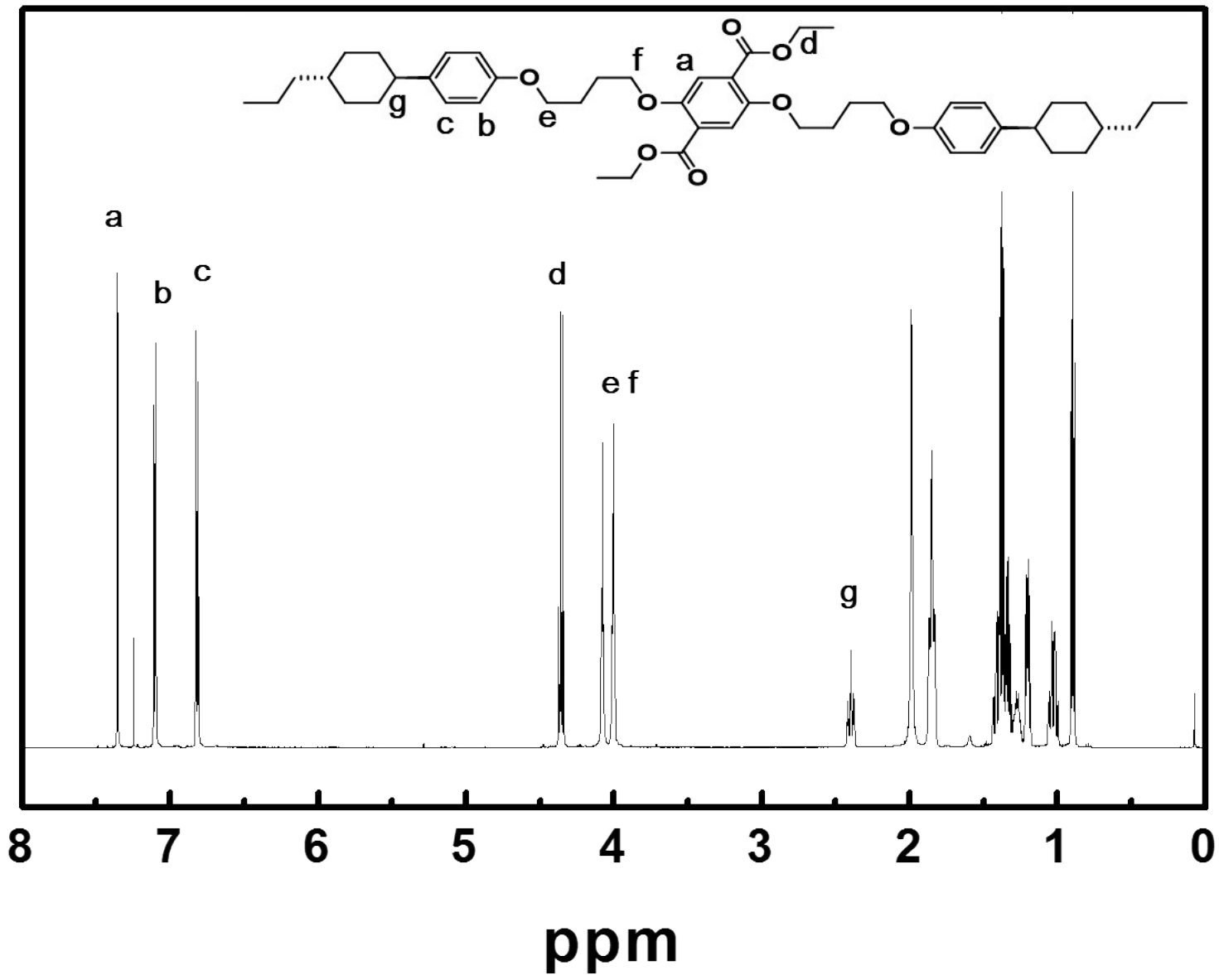

Figure S2. HNMR spectra of DEP304

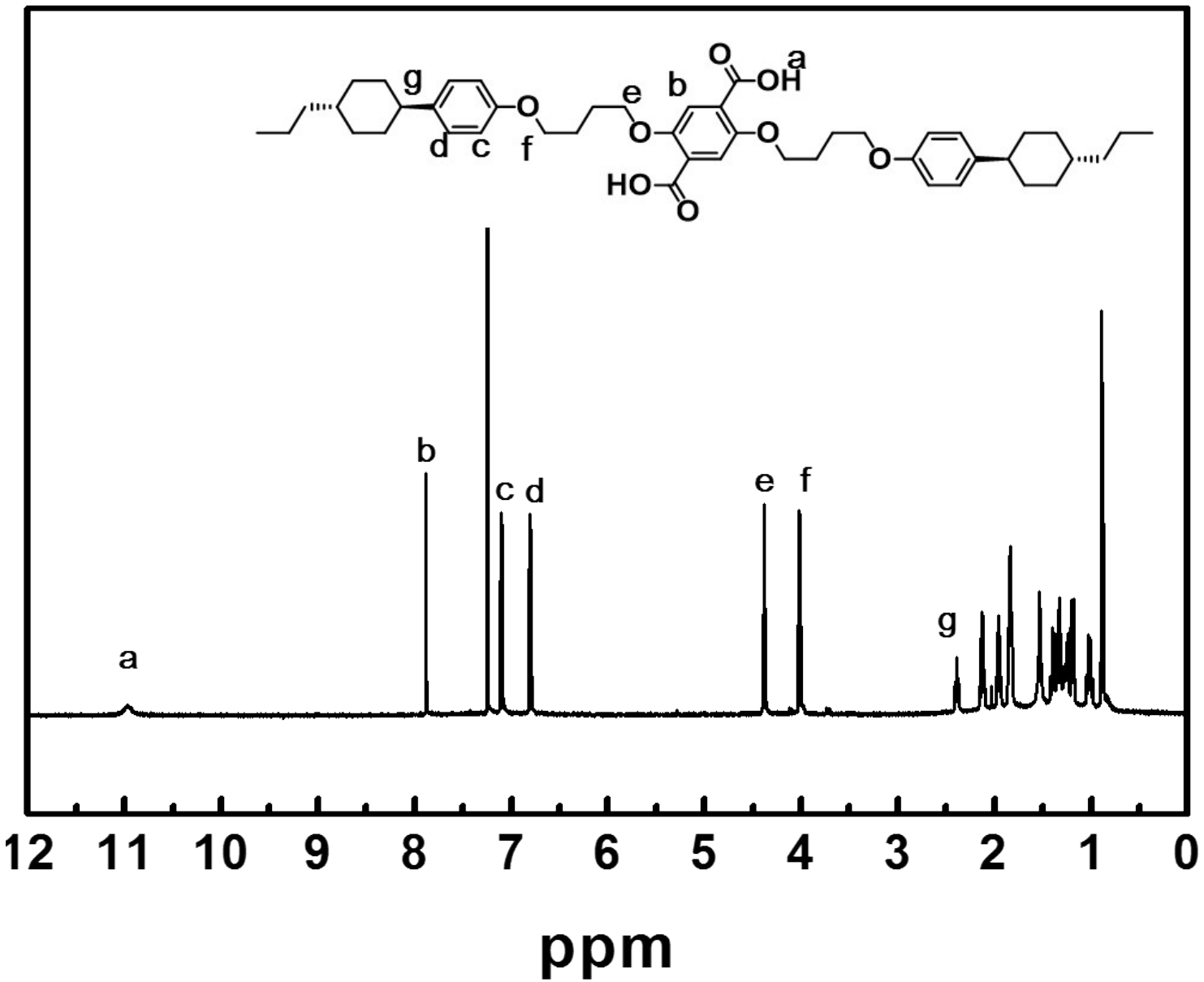

Figure S3. HNMR spectra of DCP304

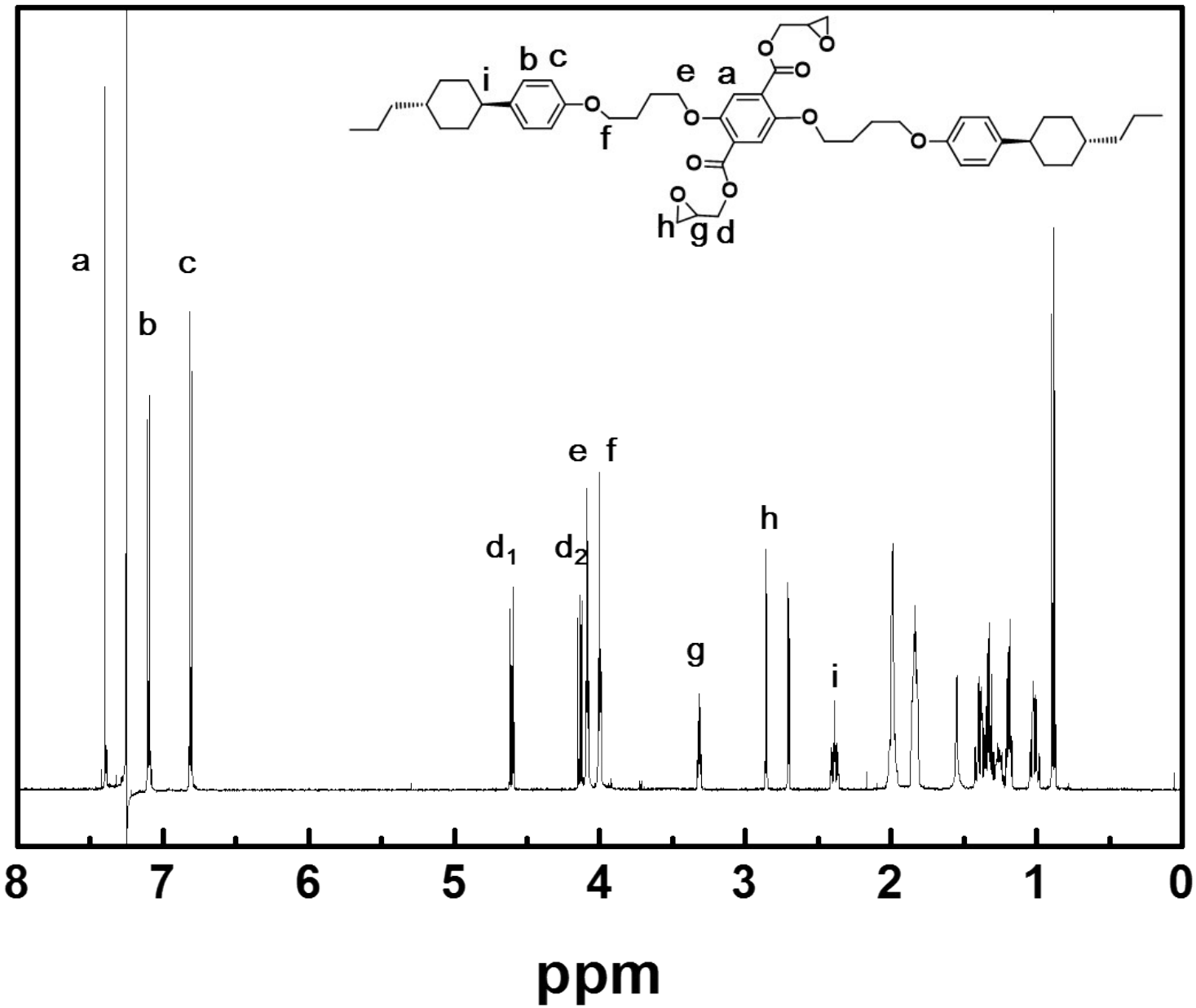

Figure S4. HNMR spectra of DGP304

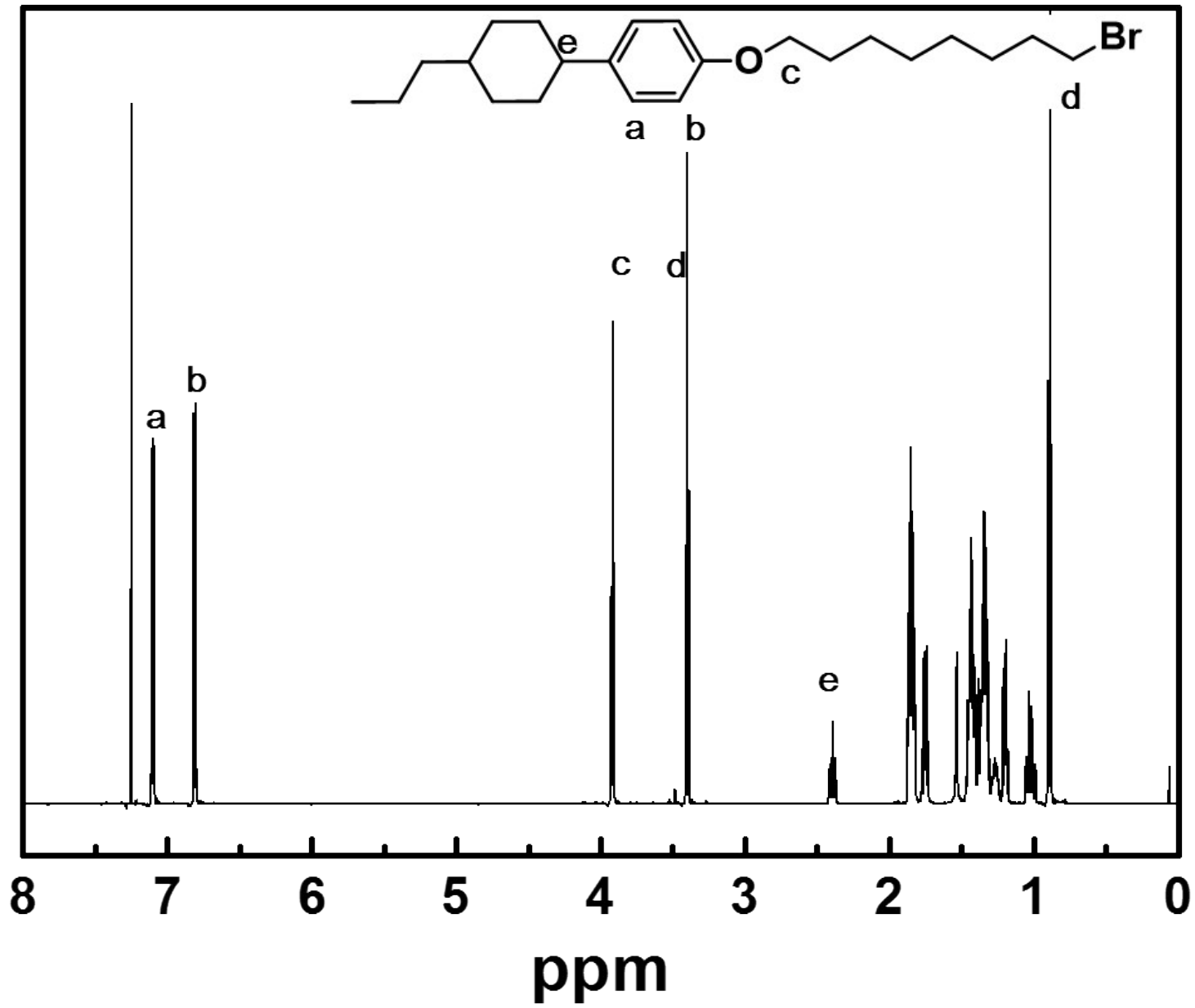

Figure S5. HNMR spectra of PCH308Br

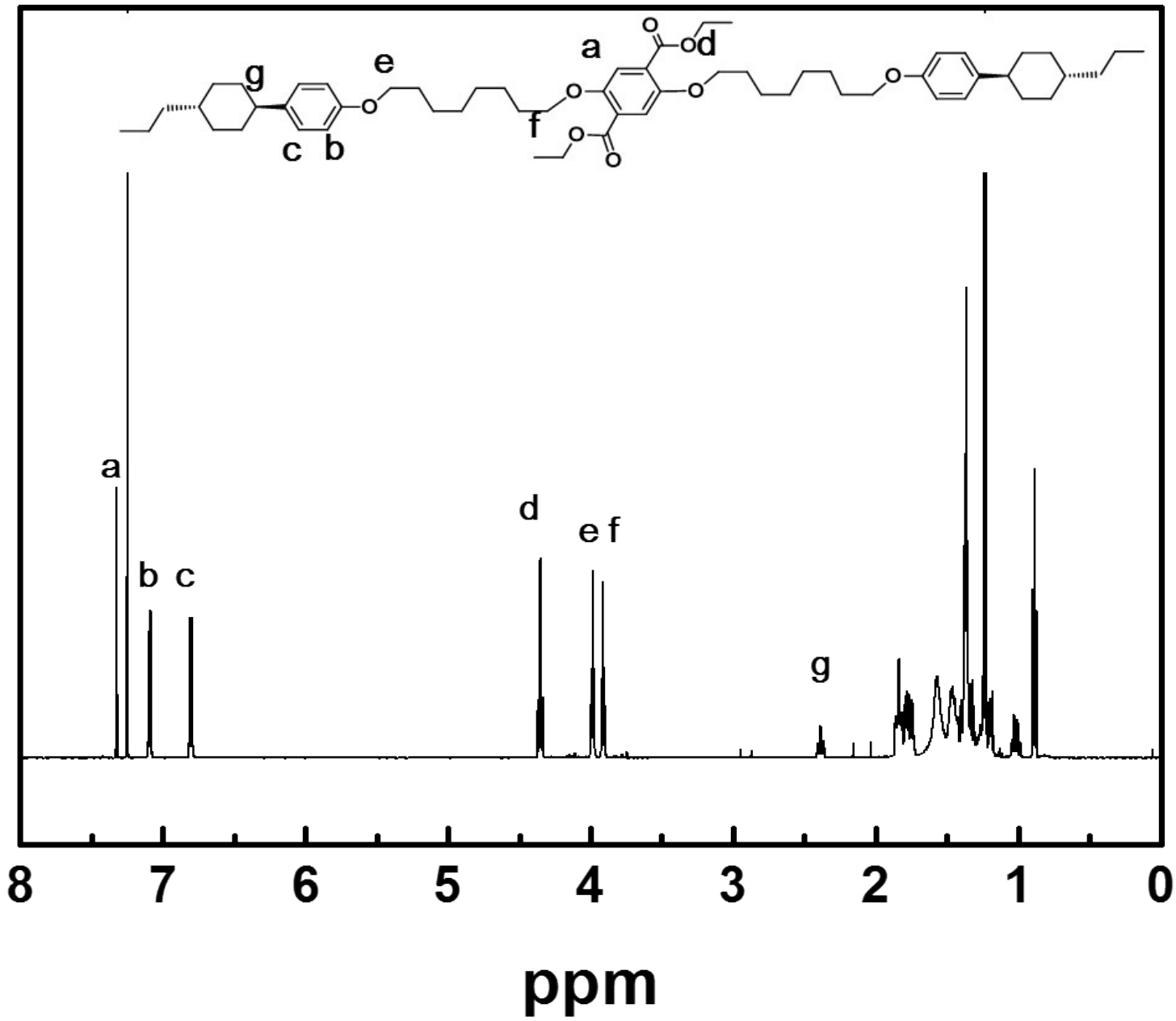

Figure S5. HNMR spectra of DEP308

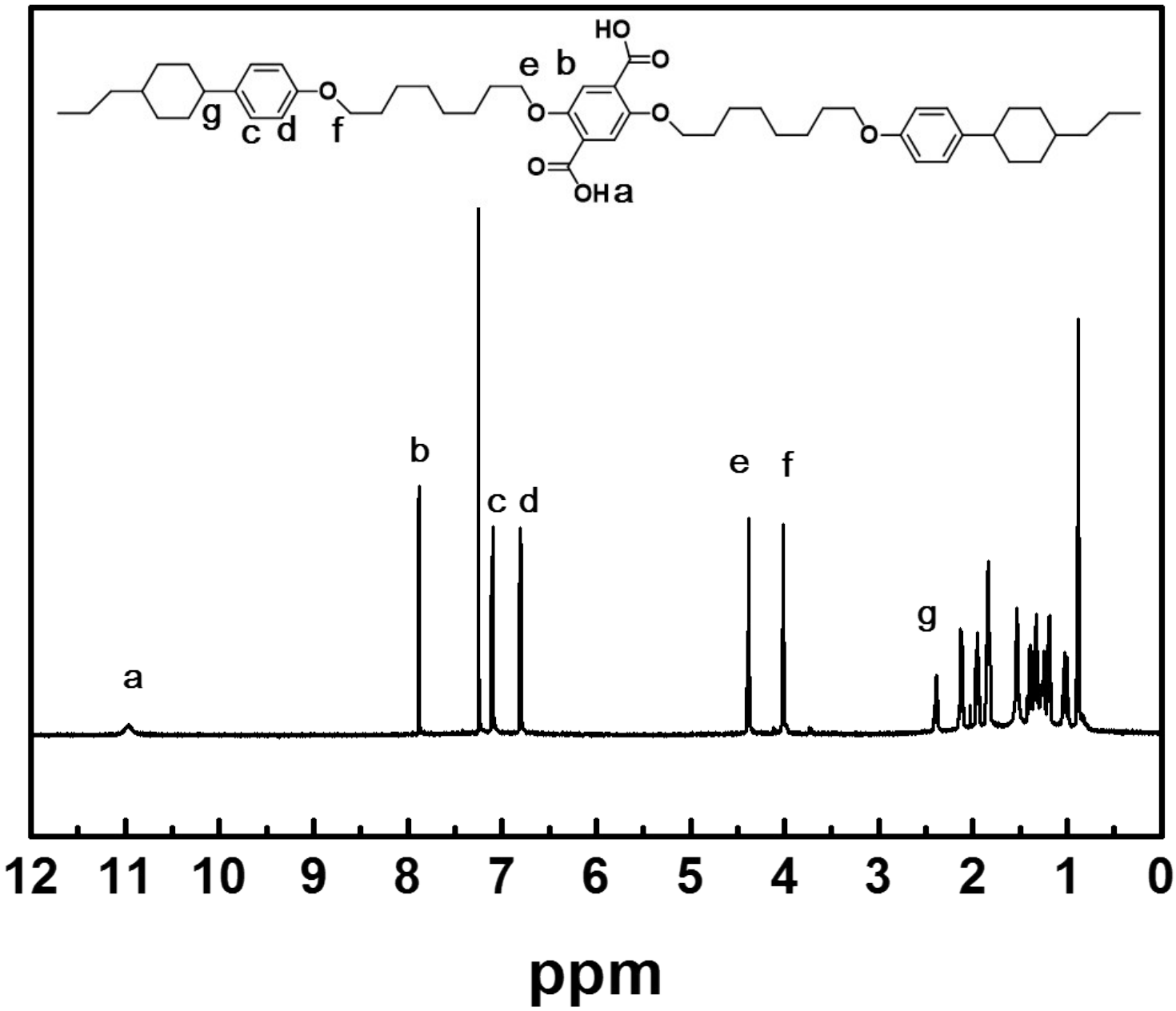

Figure S6. HNMR spectra of DCP308

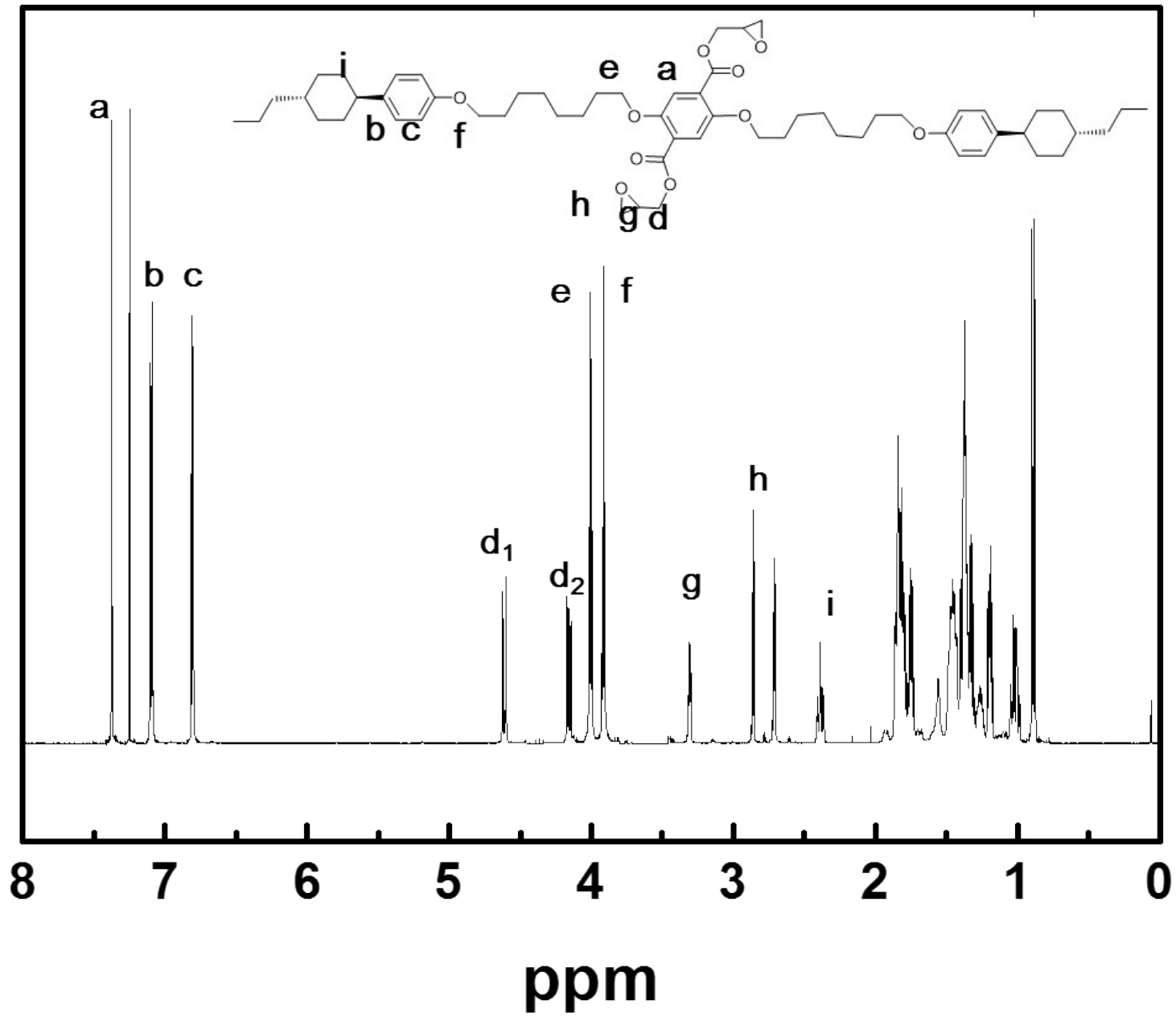

Figure S7. HNMR spectra of DGP308

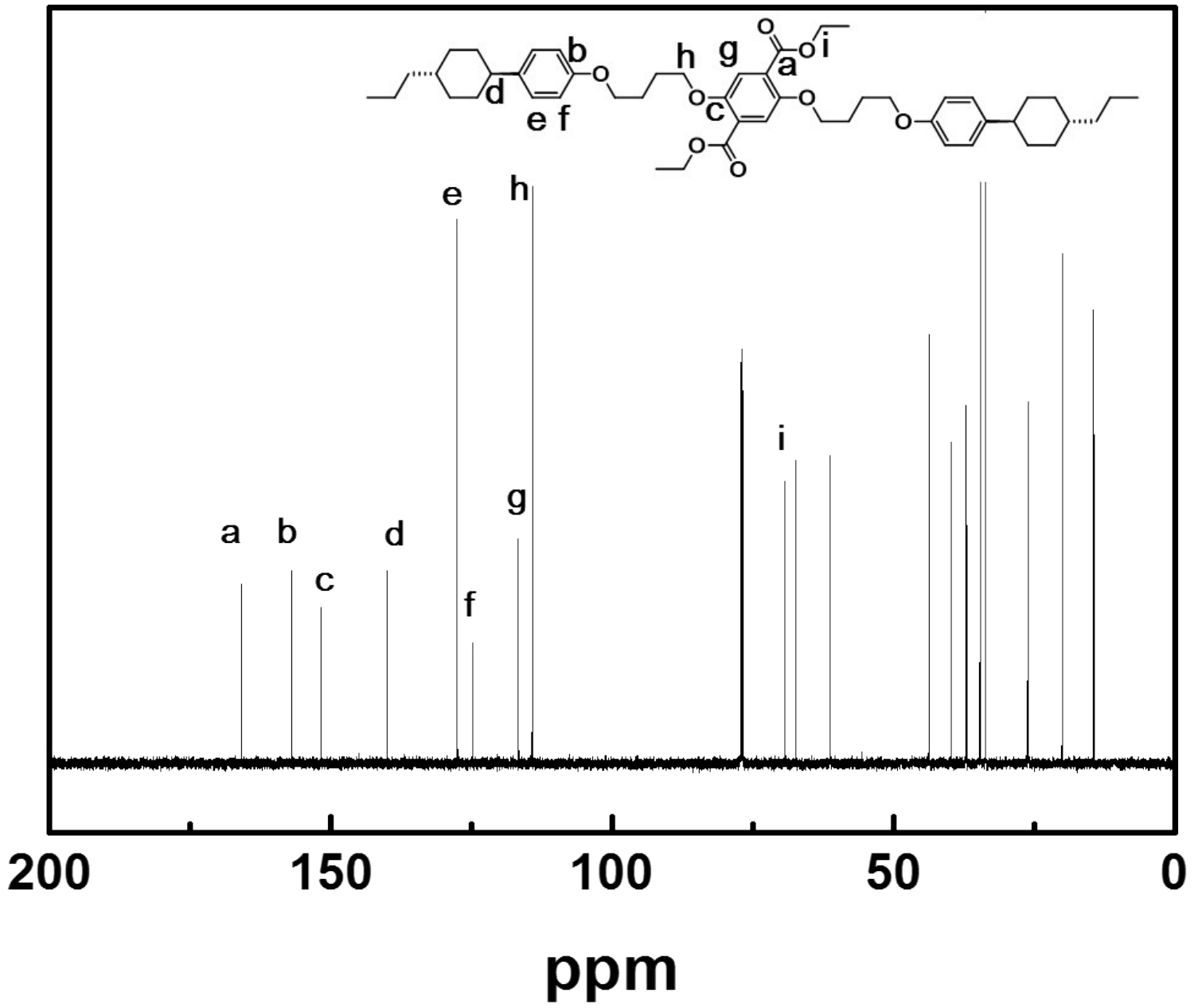

Figure S8. CNMR spectra of DEP308

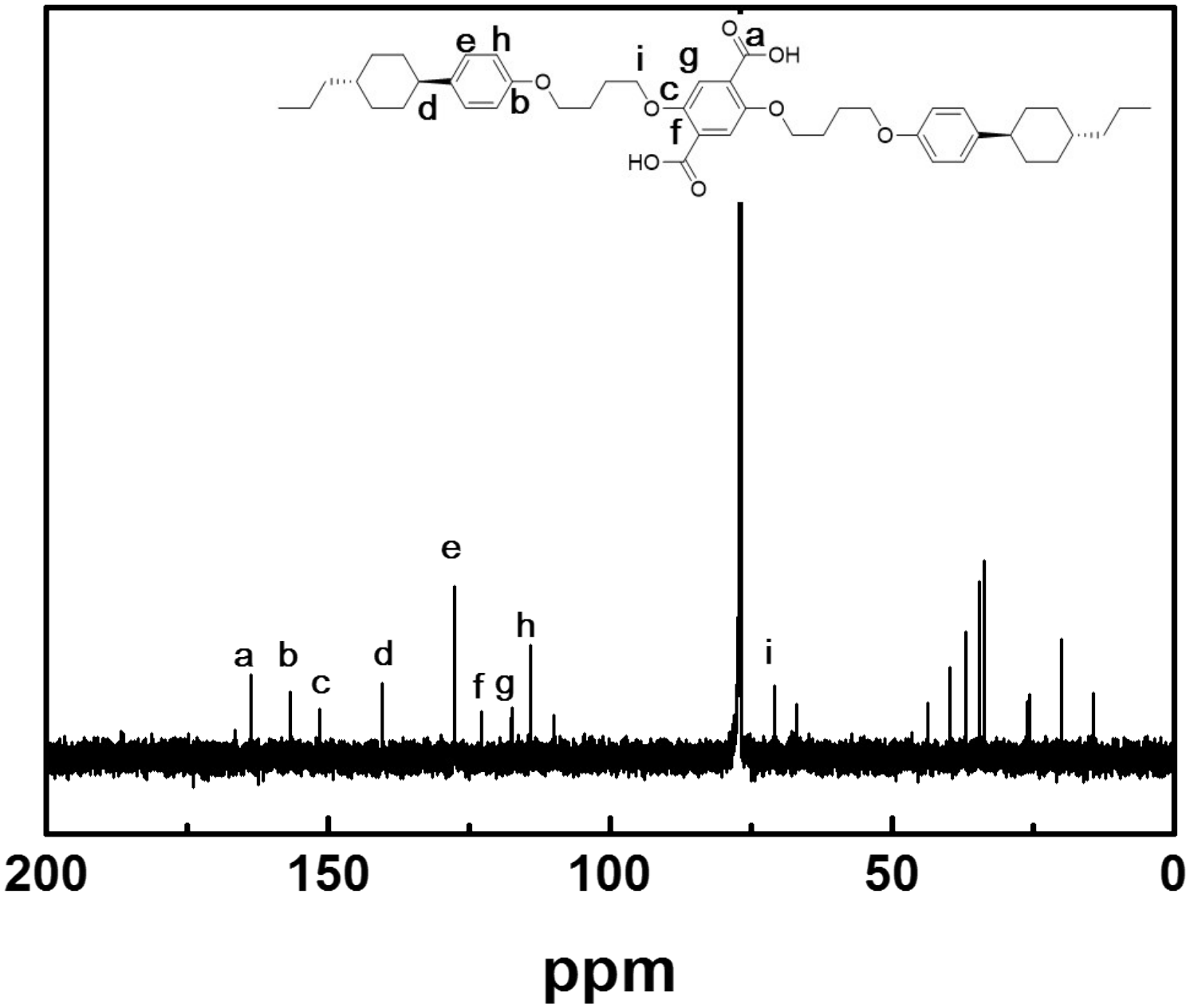

Figure S9. CNMR spectra of DCP308

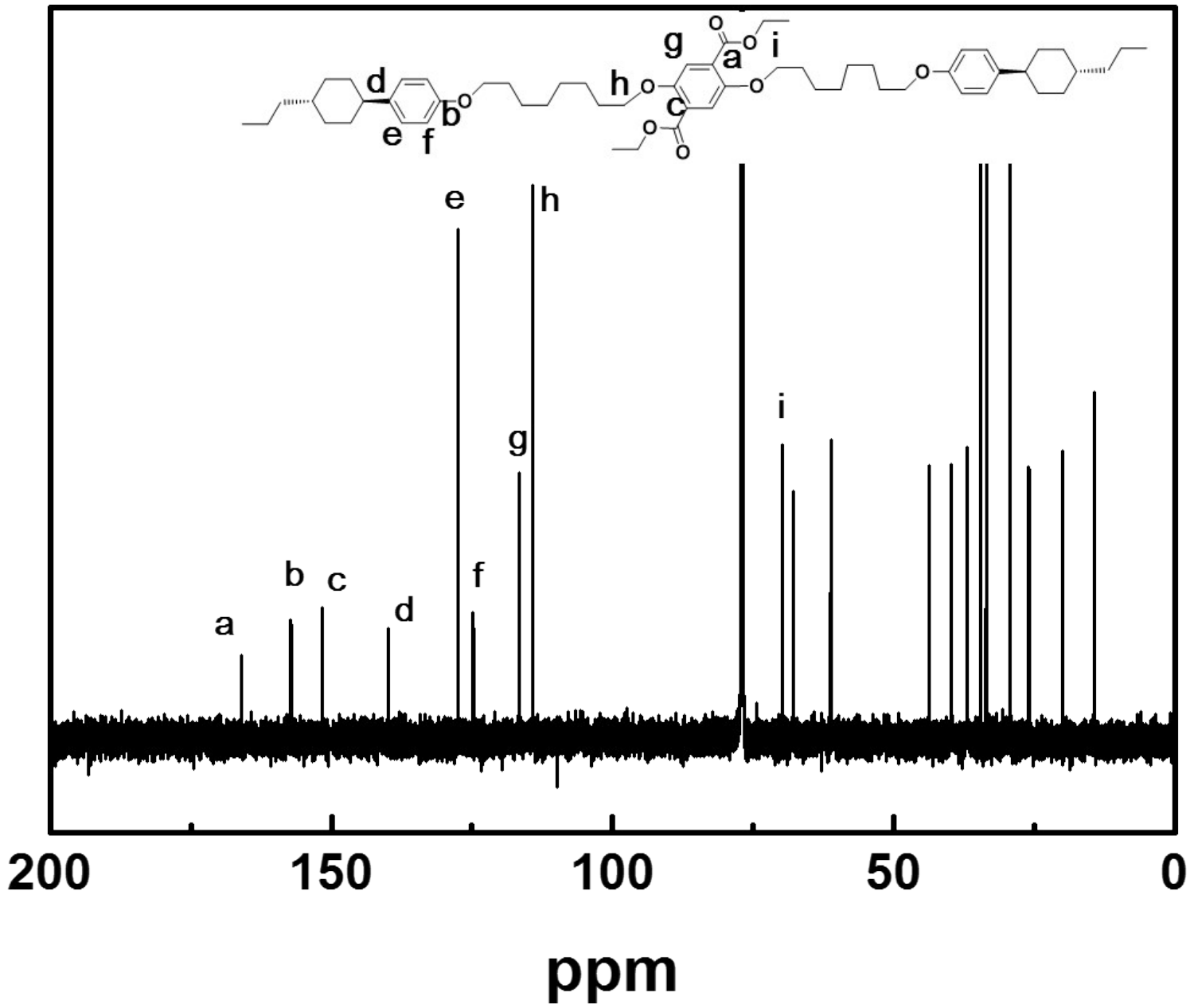

Figure S10. CNMR spectra of DEP308

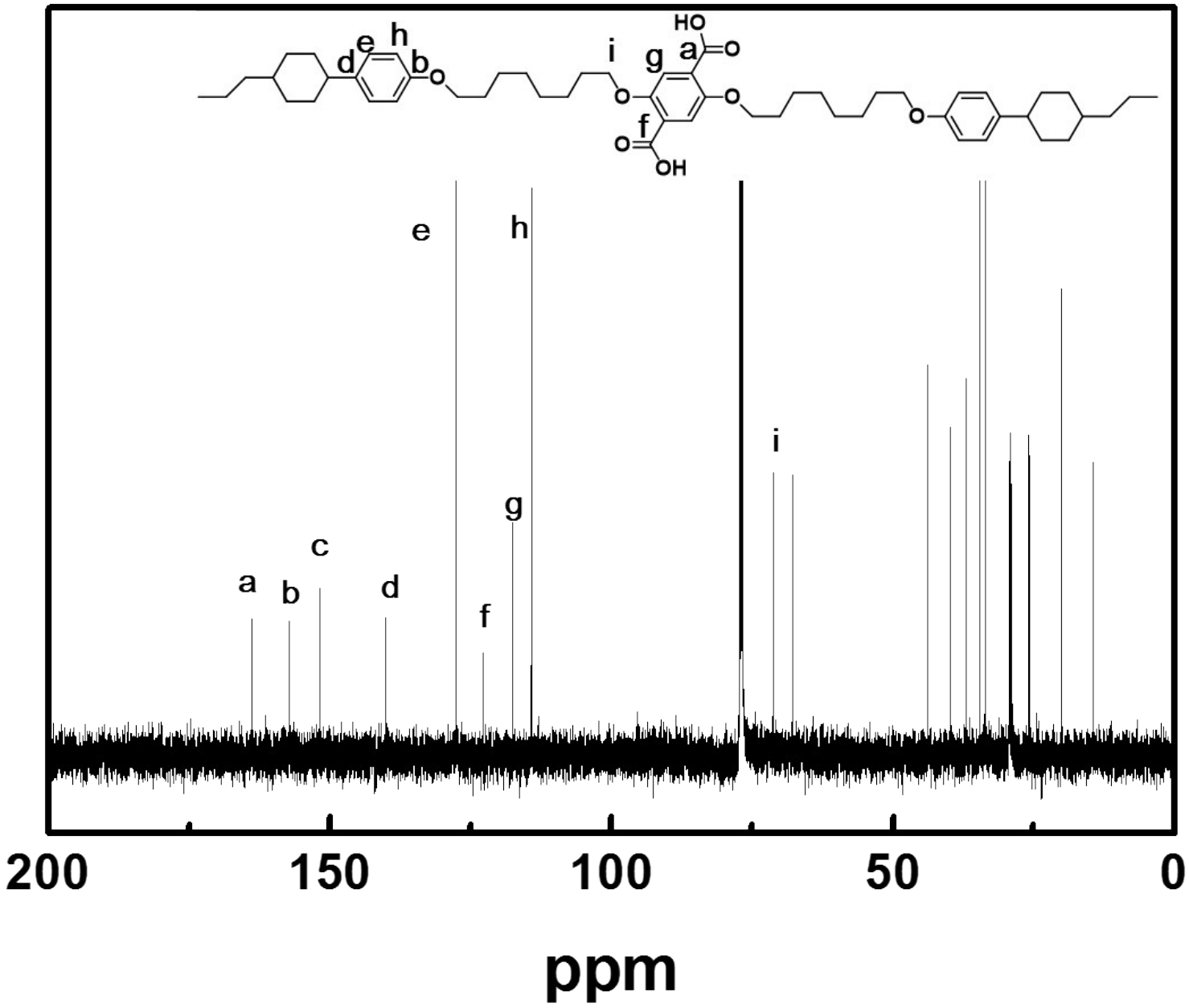

Figure S11. CNMR spectra of DCP308

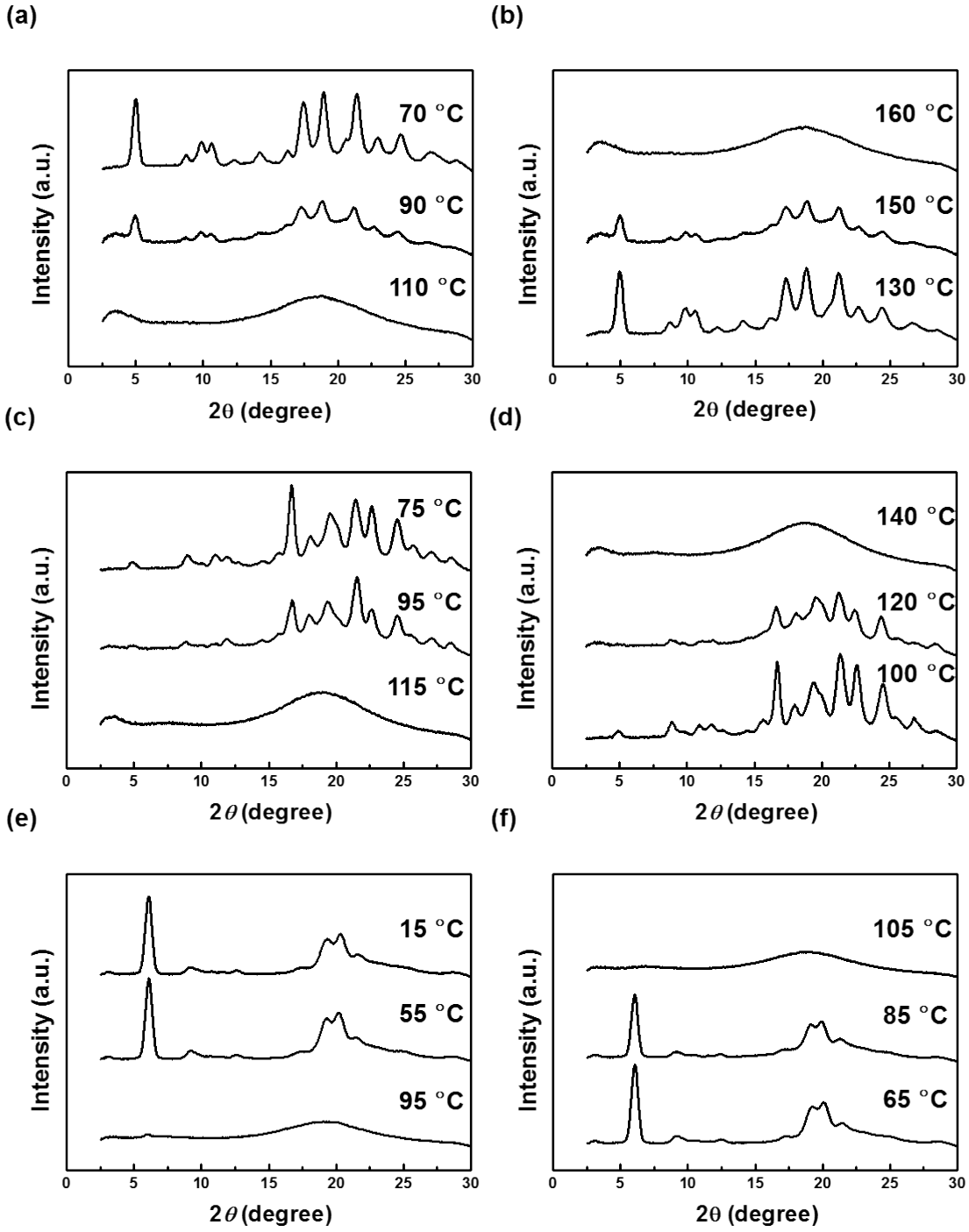

Figure S12. XRD patterns of (a, b) DGP304, (c, d) DGP306, and (e, f) DGP308 in the 1st cooling scan (a, c, e) and 2nd heating scan (b, d, f).

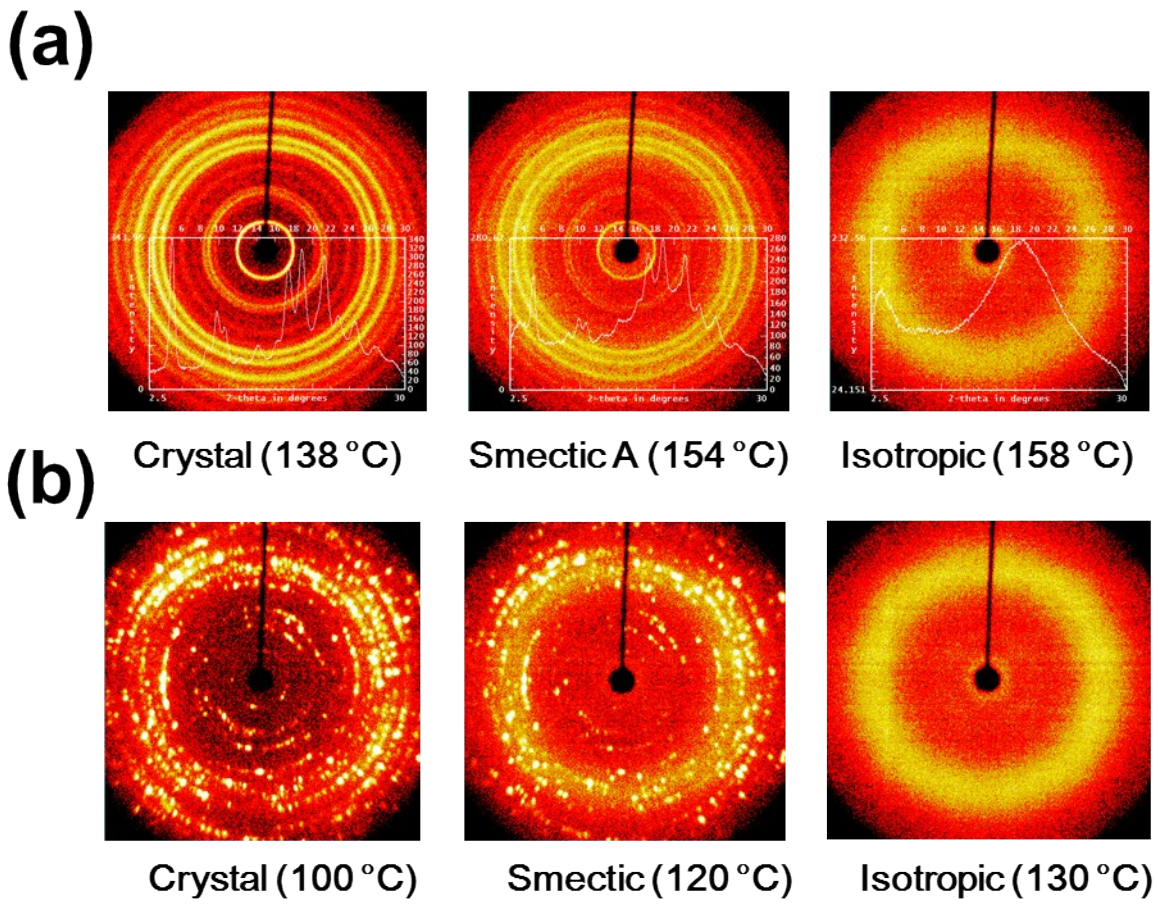

Figure S13. 2DXRD patterns of DGP30X epoxy (a) DGP304, (b) DGP306

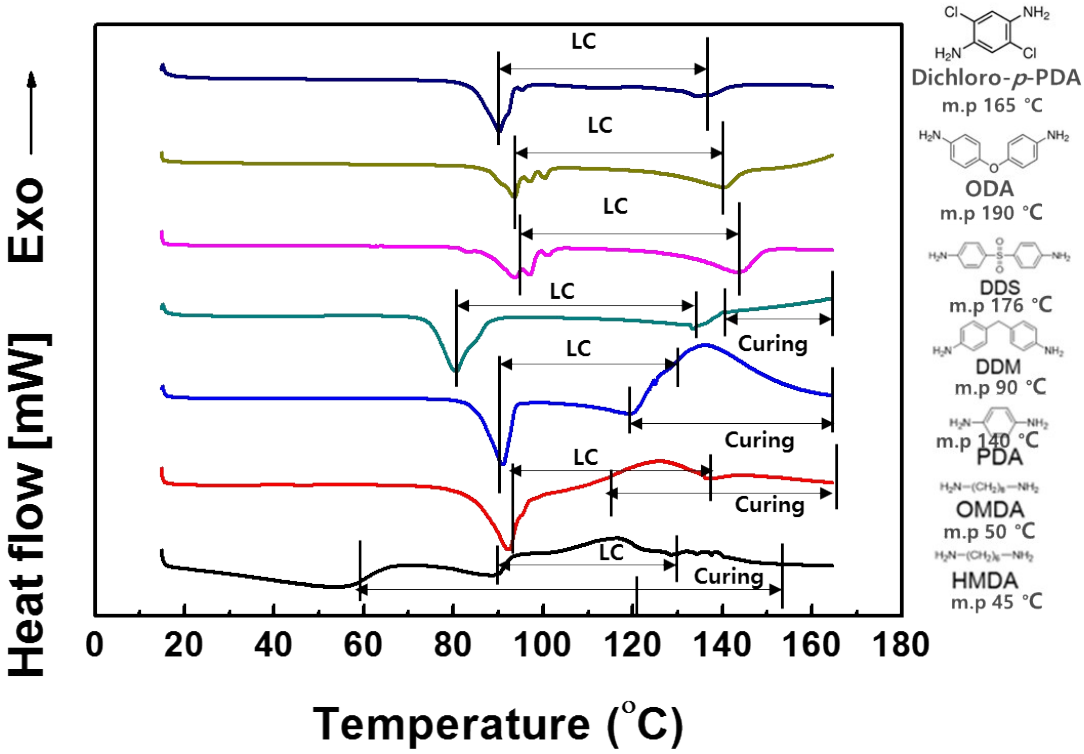

Figure S14. DSC thermograms for mixtures of System 2 and curing agents in the 1st heating scan

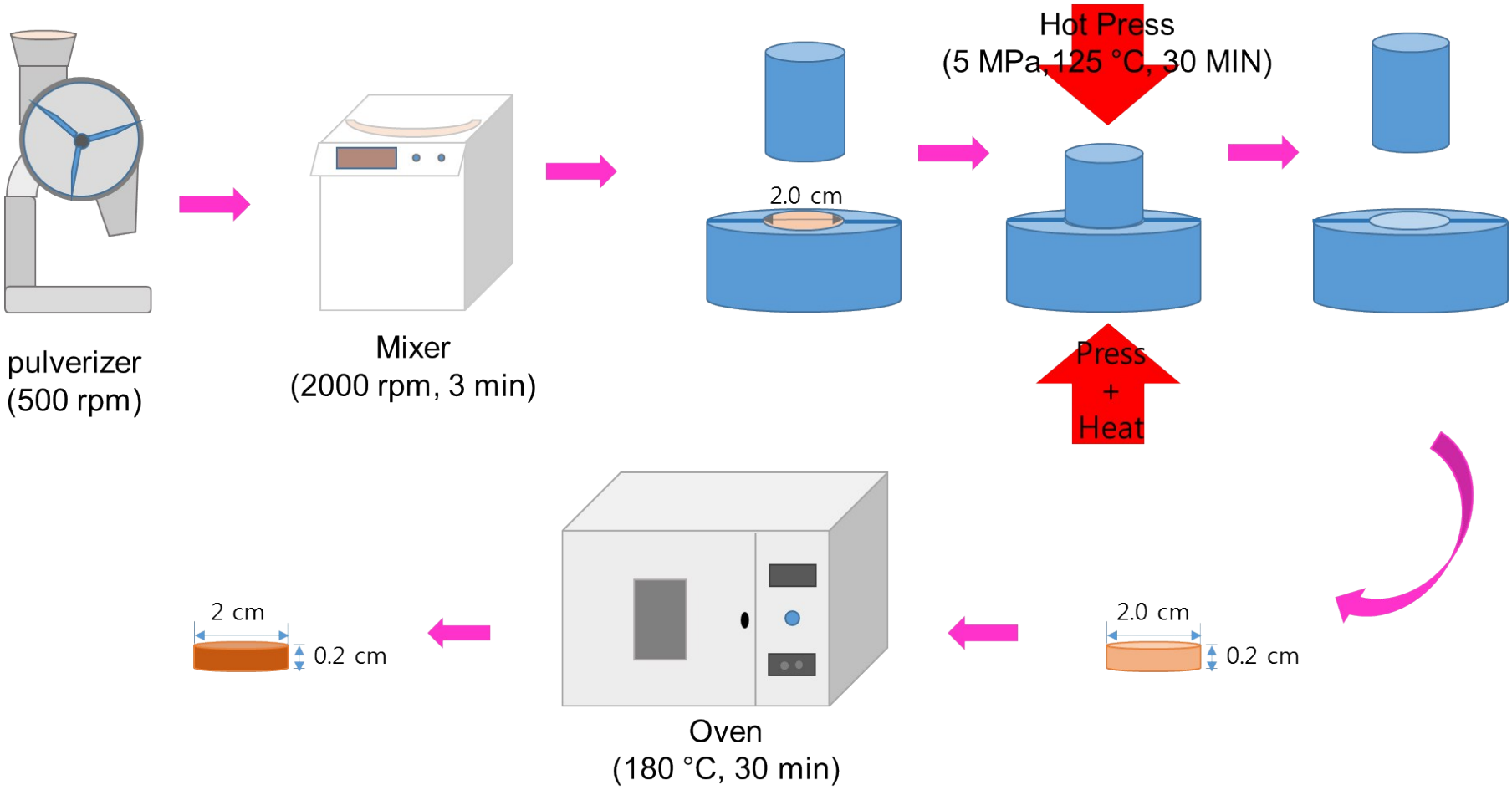

Figure S15. Procedure of sample of System 2/PDA by using hot-press